

ABSTRACT

An object of the present invention is to provide a technique capable of efficiently and precisely measuring temperature of wafers of various film kinds in a wafer processing device for processing a wafer by heating using an electromagnetic wave and realizing process with excellent product quality. To achieve it, a wafer processing device of the present invention includes a processing chamber disposed in a vacuum vessel; a wafer stage disposed in the processing chamber and having a top face on which a wafer to be processed is placed; a lamp disposed above the wafer stage and radiating an electromagnetic wave to the inside of the processing chamber including the wafer stage; an electromagnetic wave transmissive member disposed movably in the wafer stage and transmitting the electromagnetic wave; and a detector receiving the electromagnetic wave passed through the wafer and the electromagnetic wave transmissive member and detecting temperature of the wafer from a reception light spectrum.